



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-03-16
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	I9Z7*UH01BB6	A	0959	2018-03-16
Amount	UoM	Unit type	ST ECOPACK Grade	
500	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3.9-4.9-1.25	20	GULL WING	
Comment	Package: SO 20 .30 TO JEDEC MS-013 - MDF valid for CPs: L4979MD013TR and L4979MD			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	TRUE		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	FALSE		
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-15th January 2018				
Query	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	I927*UH018B6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.099	mg	supplier	die	Silicon (Si)	7440-21-3		2.986	mg	963537	5972
				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	7099	44
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	968	6
				supplier	Passivation	Silicon Nitride	12033-89-5		0.005	mg	1613	10
				supplier	Passivation	Silicon Oxide	7631-86-9		0.060	mg	19361	120
				supplier	polymer die coating	PIXL Gamma-butyrolactone	96-48-0		0.023	mg	7422	46
Leadframe	M-004 Copper and its alloys	172.144	mg	supplier	alloy	Copper (Cu)	7440-50-8		171.920	mg	998699	343840
				supplier	alloy	Iron (Fe)	7439-89-6		0.172	mg	999	344
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.052	mg	302	104
Die attach		0.775	mg	supplier	glue	Silver (Ag)	7440-22-4		0.662	mg	854194	1324
				supplier	glue	Dodecyl acrylate	2156-97-0		0.019	mg	24516	38
				supplier	glue	methylene diacrylate	42594-17-2		0.062	mg	80000	124
				supplier	glue	Diglycidylphenyl glycidyl ether	13561-08-5		0.016	mg	20644	32
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.008	mg	10323	16
				supplier	glue	dimethylbenzyl peroxide	80-43-3		0.008	mg	10323	16
Bonding wires	M-011 Other inorganic materials	0.088	mg	supplier	wire	Copper (Cu)	7440-50-8		0.088	mg	1000000	176
Encapsulation	M-011 Other inorganic materials	323.894	mg	supplier	mold compound	Silica, vitreous	60676-86-0		280.168	mg	864999	560336
				supplier	mold compound	Epoxy resin	25068-38-6		32.389	mg	99999	64778
				supplier	mold compound	Phenol resin	29690-82-2		9.717	mg	30001	19434
				supplier	mold compound	Carbon black	1333-86-4		1.620	mg	5001	3240